

- . One of the best Lm/W, Lm/\$ in Mid---Power LED （高光效、高性价比）
- . Mid---POWER EMC PACKAGING LED – 3030 R、Y SERIES （LED---3030 红、黄光系列）

T3C\*\*011C\*\*AA



### Product Brief（产品简介）

#### FEATURES AND BENEFITS（特性优点）

- . HIGH LUMEN OUTPUT AND EFFICACY（高流明和高光效）
- . DESIGNED FOR HIGH CURRENT OPERATION（高电流使用）
- . LOW THERMAL RESISTANCE（低热阻）
- . PB---FREE REFLOW SOLDERING APPLICATION（适用无铅回流焊）

### Key ApplicaEons（应用）

- TURNING LAMP
- CHMSL
- STOP LAMP
- SIGNAL LAMP
- REAR LAMP
- TURNING LAMP

### Table1.ProductSeleceonTable（产品目录）

Model No.	WD 波长(nm)	
	Min.	Max.
T3CRE011C**AA	620	630
T3CYE011C**AA	585	595



## Performance Characteristics (特性参数)

Table 2. Electro-Optical Characteristics (光电特性),  $I_F = 150\text{mA}$ ,  $T_a = 25^\circ\text{C}$ , RH60%

Color	Typical Luminous Flux( $I_F=150\text{mA}$ )	
	Typ	Min
RED	19	17
YELLOW	19	17

- Tolerance of measurements of the Luminous Flux is  $\pm 7\%$  ( LM 测试误差 $\pm 7\%$  ) .
- The lumen table is only for reference ( LM 参数供参考 ) .
- $T_a = 25^\circ\text{C}$ , RH60% ( 温度:  $25^\circ\text{C}$ , 湿度: 60% ) .



## Performance CharacterisEcs (特性参数)

Table3.ElectroOpEcalCharacterisEcs (光电特性) , IF = 150mA , Ta = 25℃ , RH60%

Item 参数	Symbol 符号	Colour	Value 数值			Unit 单位	Test Condifon 测试条件
			Min 最小值	Typ 典型值	Max 最大值		
Forward Voltage 正向电压	VF	RED	---	2.0	2.4	V	IF=150mA
		YELLOW	---	2.2	2.4		
Reverse Current 反向电流	IR	RED	---	---	10	μA	VR=5V
		YELLOW					
View Angle 发光角度	2θ1/2	RED	---	120	---	°	IF=150mA
		YELLOW					
Thermal Resistance 热阻	(Rth j---sp)	RED	---	14	---	℃/W	IF=150mA
		YELLOW	---	16	---		
Electrostaafc Discharge 抗静电	ESD	RED	---	---	8000	V	HBM
		YELLOW	---	---	8000		

- Tolerance : VF :±0.08V (VF 测试误差±0.08V) .
- 2θ1/2 is the off---axis where the luminous intensity is 1/2 of the peak intensity (2θ1/2 即为发光强度为峰值强度 1/2 的角度) .
- Thermal resistance : RthJS (Juncfon / solder) 热阻值 (结点至焊点) .
- Ta = 25℃ , RH60% (温度: 25 ℃ , 湿度: 60%) .



## Performance Characteristics (特性参数)

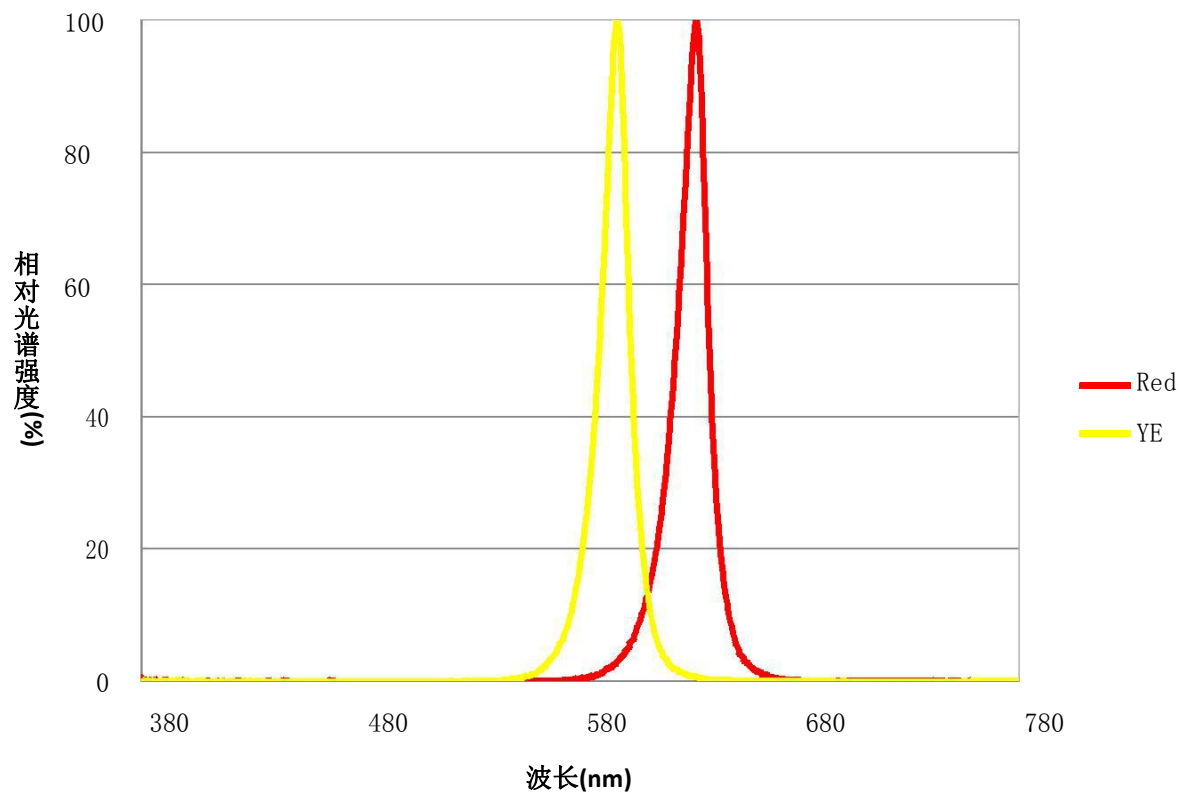
Table 4. Absolute Maximum Ratings (最大额定参数), Ta = 25°C, RH60%

Item 参数名称	Symbol 符号	Absolute Maximum Ratings 最大额定参数		Unit 单位
Forward Current 正向电流	IF	RED	350	mA
		YELLOW	240	
Pulse Forward Current 正向脉冲电流	IFP	RED	400	mA
		YELLOW	300	
Power Dissipation 功率损耗	PD	RED	840	mW
		YELLOW	624	
Reverse Voltage 反向电压	VR		5	V
Operating Temperature 操作温度	Topr		-40~+105	°C
Storage Temperature 储存温度	Tstg		-40~+105	°C
Junction Temperature 结温	Tj		125	°C
Soldering Temperature 回流温度	Tsld		230°C or 260°C for 10sec	

- IFP condition with Pulse: Width ≤ 100μs Duty cycle ≤ 1/10
- LED's properties might be different from suggested values like above and below tables if operation condition will be exceeded our parameter range. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
- 正向脉冲电流条件: 脉冲宽度 ≤ 100μs, 占空比 ≤ 1/10
- 操作条件若超出最大额定参数, 可能会对 LED 造成不可预期伤害。

## Relative Spectral Distribution (光谱分布)

Fig 1. Band energy characteristic (波段能量特性曲线图),  $T_a = 25^\circ\text{C}$ , RH60%



## Forward Current CharacterisEcs (IV 特性曲线)

Fig 2. IF----- RelaEve Luminous flux, Ta = 25°C  
(亮度与电流关系, 温度=25°C)

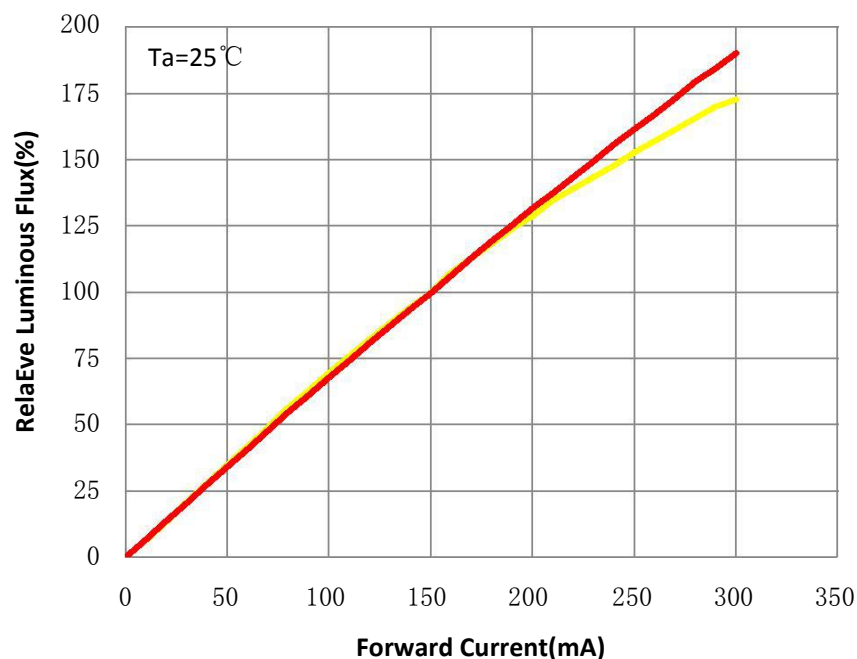
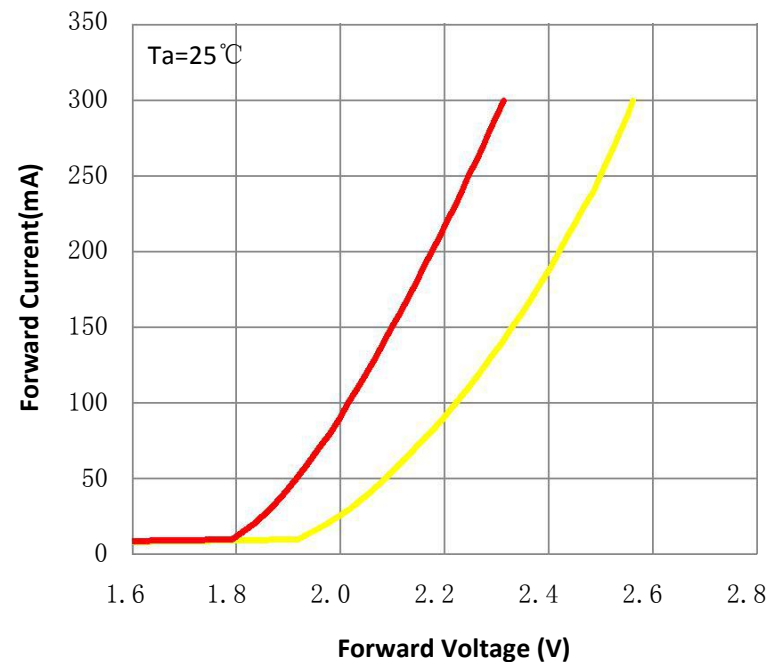


Fig 3. Forward Voltage vs. Forward Current, Ta = 25°C  
(电压与电流关系, 温度=25°C)





## Iv & Vf VS Temperature CharacterisEcs (亮度与电压 vs 温度关系)

Fig 4. Ta—RelaEveLuminousflux (温度与亮度关系)

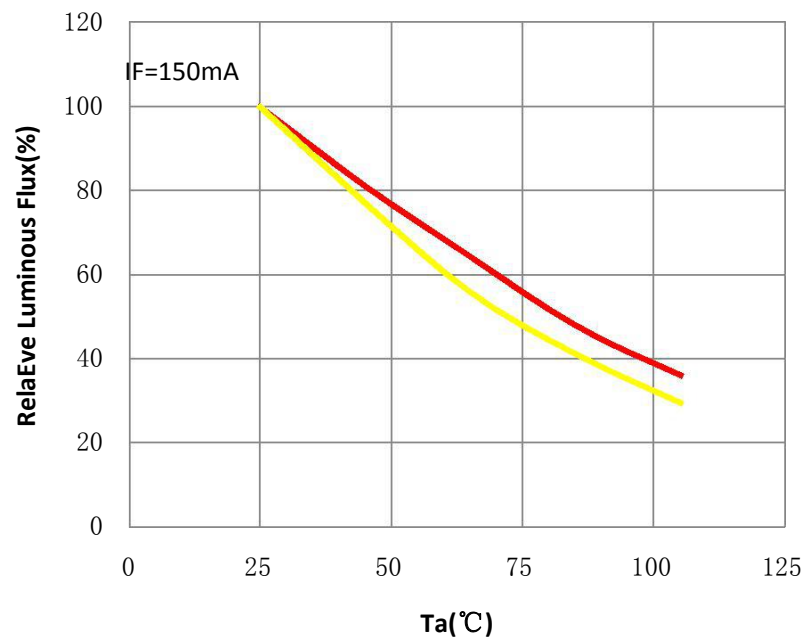
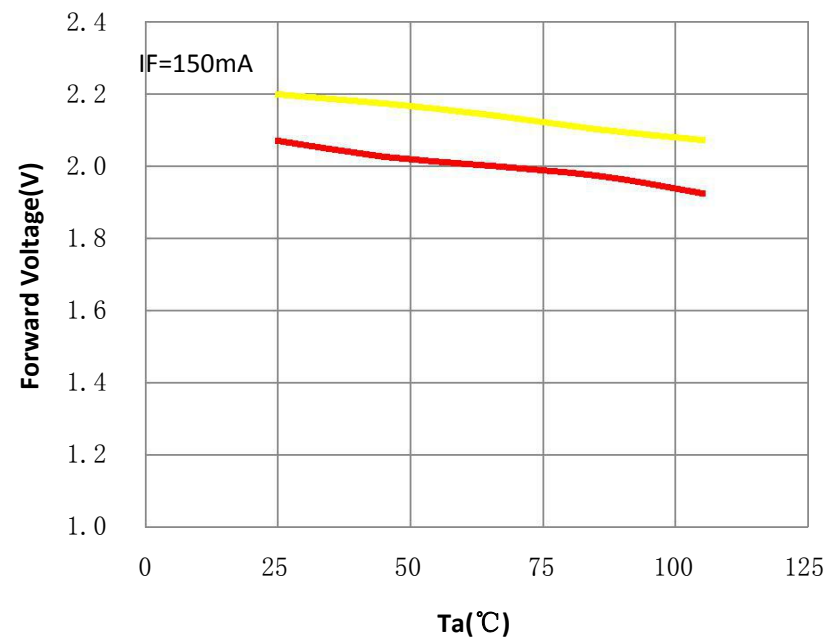


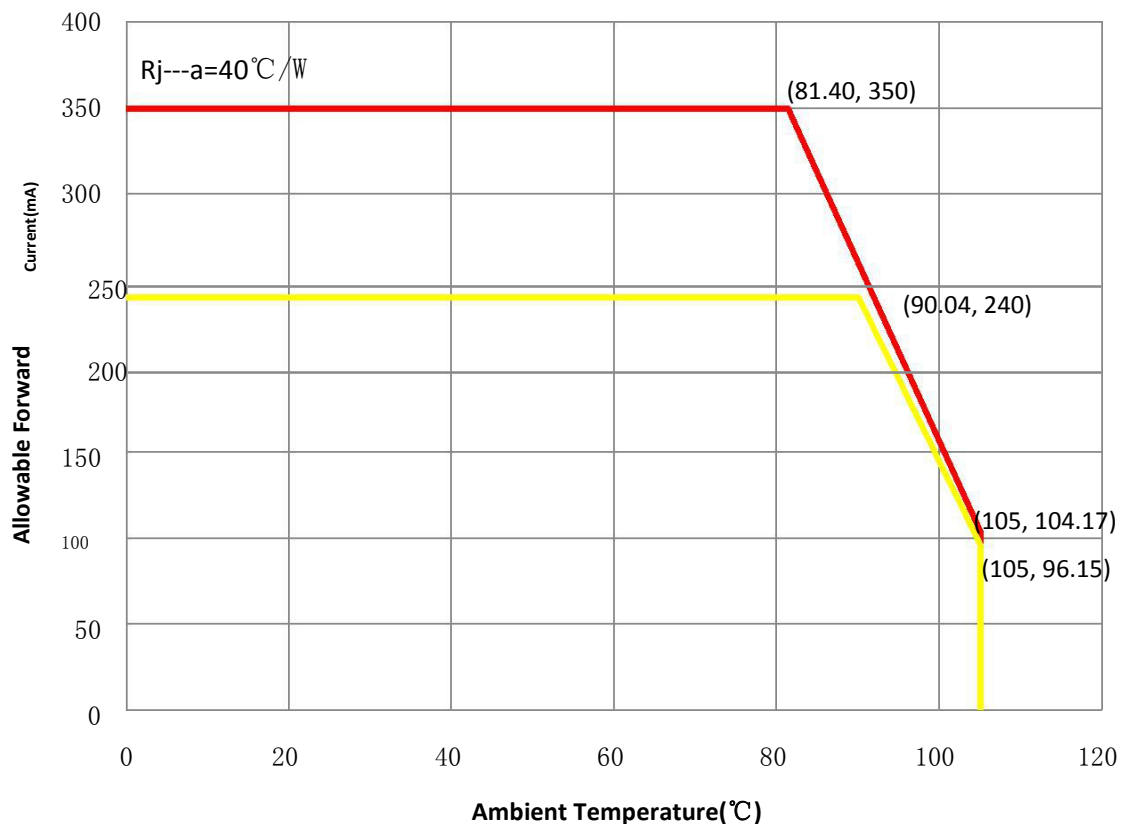
Fig 5. Ta—ForwardVoltage (温度与电压关系)





### Ambient Temperature CharacterisEcs (电流温度关系特性)

Fig6, Maximum Forward Current vs. Ambient Temperature (最大正向电流 vs 环境温度)







### WD Bin Structure (分光方式)

Table5.The main wavelength standard grading (主波长标准分档), IF = 150mA, Ta = 25°C, RH60%

Colour	Min	Max	Unit 单位
RED	620	625	nm
	625	630	nm
YELLOW	585	590	nm
	590	595	nm

- Tolerance of measurements of the WD is ±1nm (WD 的测量误差: ±1nm)。
- Ta = 25°C, RH60% (温度: 25 °C, 湿度: 60%)。



Luminous Flux Bin Structure (分光方式)

Table6. Luminous Flux Ranks (光通量分档), IF = 150mA, Ta = 25°C, RH60%

LuminousFlux (IF=150mA)		
Code	Min	Max
AG	14	18
AH	18	22
AJ	22	26

- Tolerance of measurements of the Luminous Flux is  $\pm 7\%$  (光通量的测量误差:  $\pm 7\%$ )。
- Ta = 25°C, RH60% (温度: 25 °C, 湿度: 60%)。



## Forward Voltage Bin Structure (分压方式)

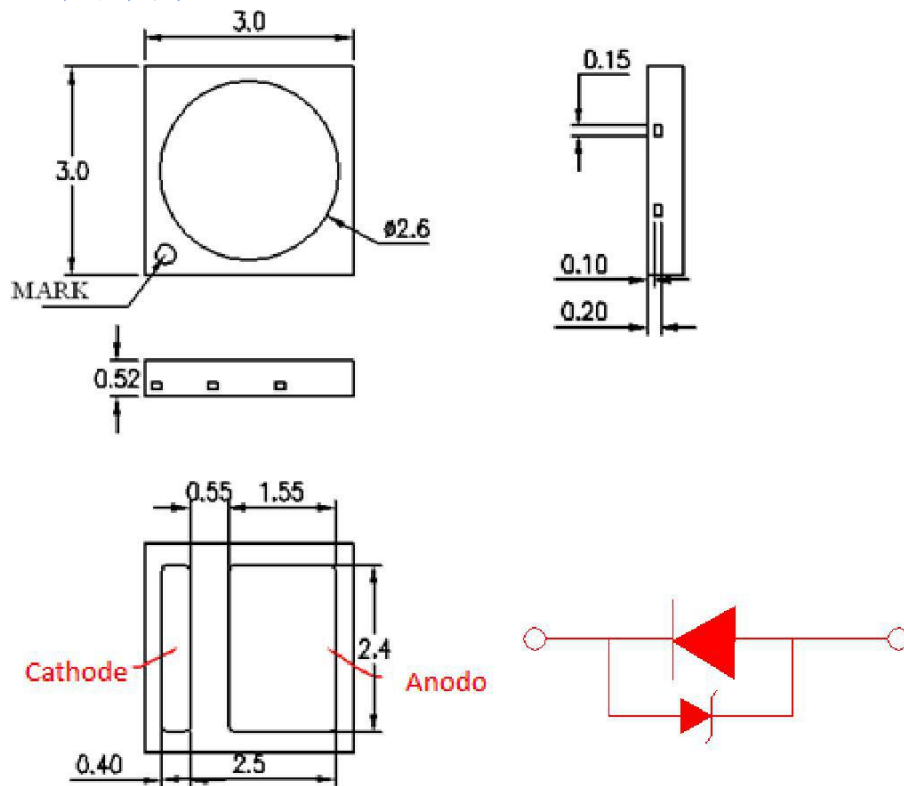
Table7. Forward Voltage Ranks (正向电压分档) , IF = 150mA , Ta = 25°C , RH60%

Colour	MIN	MAX	UNIT
RED YELLOW	1.6	1.8	V
	1.8	2.0	V
	2.0	2.2	V
	2.2	2.4	V

- Tolerance of measurements of the Forward Voltage is  $\pm 0.08V$  (正向电压的测量误差:  $\pm 0.08V$ ) .
- Ta = 25°C, RH60% (温度: 25 °C, 湿度: 60%) .

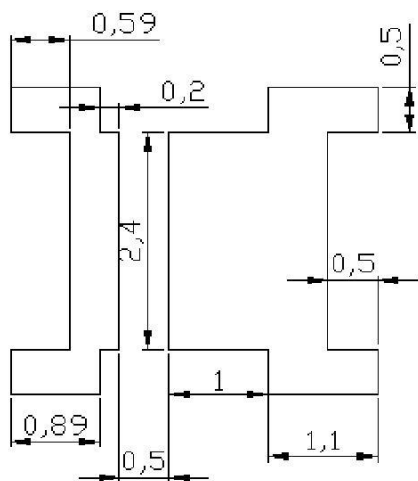
## Mechanical Dimensions (产品尺寸)

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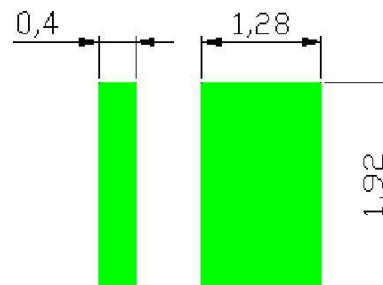


- All dimensions are in millimeters (图中所有尺寸均以毫米为单位) .
- Scale : 1:1 (比例: 1:1) .
- Undefined tolerance is  $\pm 0.2$ mm (尺寸公差: $\pm 0.2$  毫米).

## Recommended Solder Pad (焊盘设计)



**Recommended solder pad**  
建议焊盘

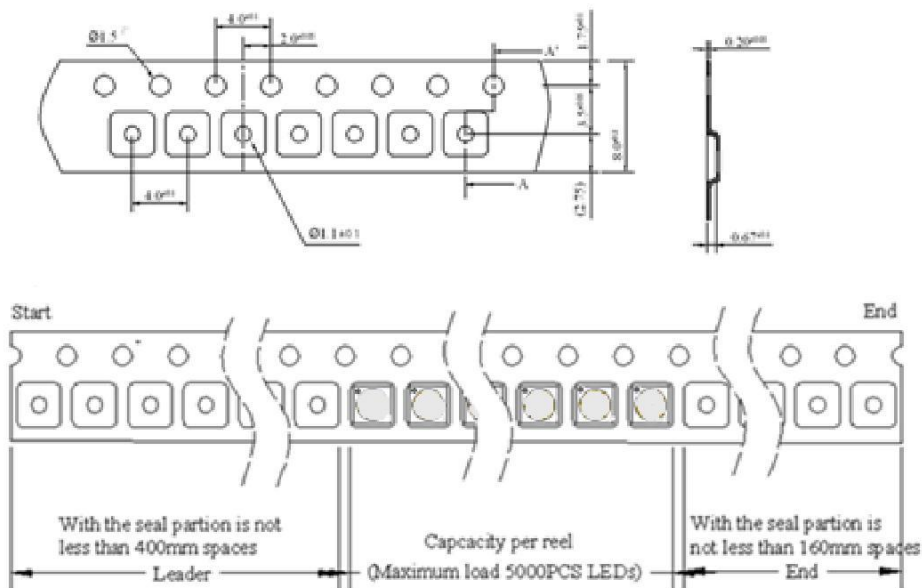


**Recommended stencil opening**  
建议钢网

- All dimensions are in millimeters
- Scale : 1:1
- This drawing without tolerances are for reference only
- Undefined tolerance:  $\pm 0.10\text{mm}$
- 图中所有尺寸均以毫米为单位
- 比例: 1:1
- 图纸仅供参考
- 若无特殊标注, 图中公差尺寸为 $\pm 0.10\text{mm}$

## Packaging Information (包装信息)

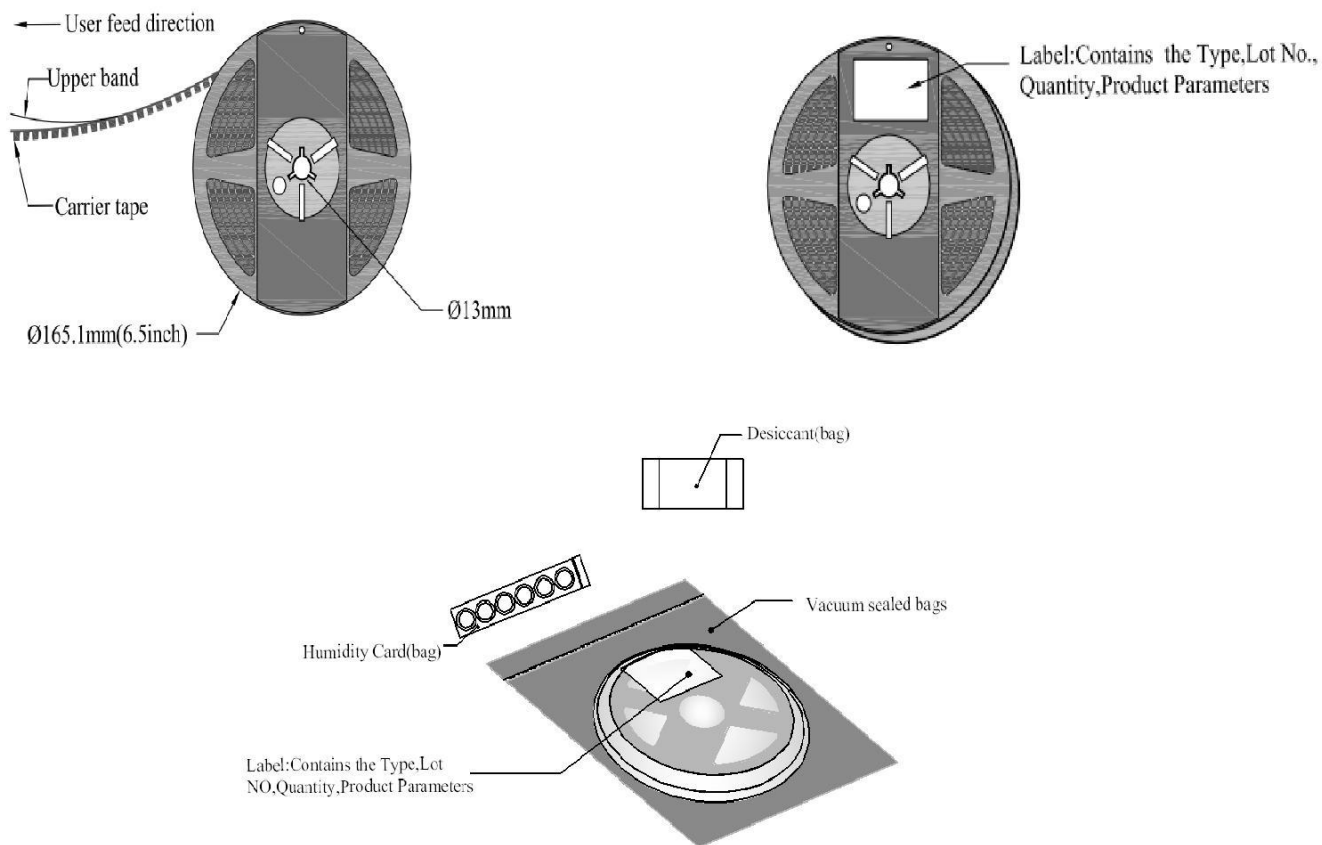
### Reel Packaging (卷带包装)



- Quantity : Max 5000pcs/Reel
- Cumulative Tolerance : Cumulative Tolerance/10 pitches to be  $\pm 0.2\text{mm}$
- Adhesion Strength of Cover Tape Adhesion strength to be 0.1---0.7N when the cover tape is turned off from the carrier tape at the angle of  $10^\circ$  to the carrier tape.
- Package : P/N, Manufacturing data Code No. and Quantity to be indicated on a damp proof Package
- 数量: 最多 5000pcs/卷
- 10 pitches 累积公差  $\pm 0.2\text{mm}$
- 上带剥离强度为 0.1---0.7N (上带与载带成  $10^\circ$ 角剥离)
- 包装信息包含料号, 生产日期及数量等

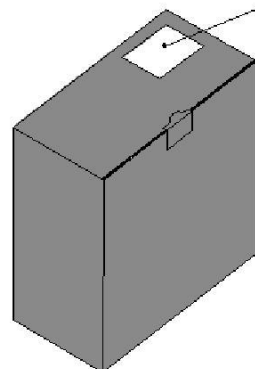
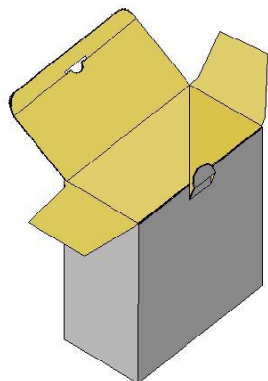
## Packaging Information (包装信息)

### Reel Packaging (卷带包装)



## Packaging Information (包装信息)

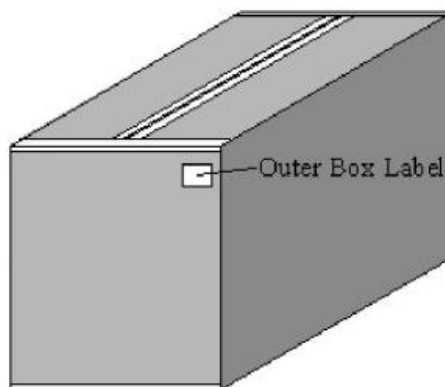
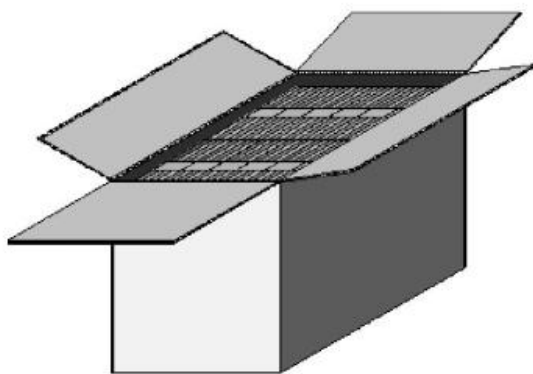
### Inner Box (内箱)



Label: Contains Type,  
Lot NO, Quantity, Product  
Parameters.

\* Capacity 5 or 10 reels per box (内箱容量: 5 或 10 卷)

### Outer Box (外箱)



### Label (标签)

Outer Box Label

\* Capacity 30 or 60 reels per box (外箱容量: 30 或 60 卷)

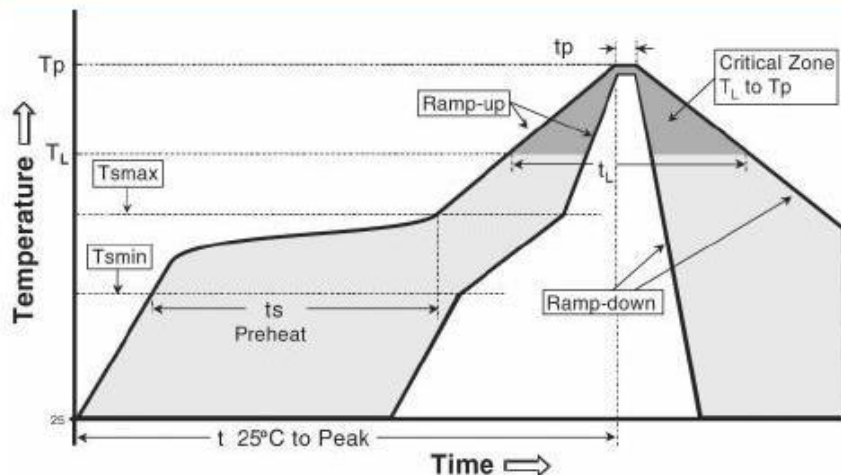


## Product Nomenclature (命名原则)

Table9.PartNumberingSystem (命名原则) : T □□ □□ □□ □□ □□ □□ □□ □□

Item Number Code 序号代码	DescripEon 描述	Content 内容
X1	Typecode 产品代码	34:3020; 3A:K285; 3B:3014; 3C:3030; 5A:5050N; 32: 3528; 19: Ceramic 3535; 15: Ceramic 5050; 12: Ceramic 9292; 20: 2016.
X2	CCT code 色温代码	BL: blue ; GR : green; YE : yellow; AM: PC Amber ; RE : red
X3	Color Rendering 显指	\
X4	No. of serial chip 晶片串联数量	1--Z.
X5	No. of parallel chip 晶片并联数量	1--Z.
X6	Component code 补充吗	A--Z
X7	Internal code1 内部码 1	\
X8	Internal code2 内部码 2	\

## Reflow Soldering CharacterisEcs (建议回流焊方式)



Reflow soldering	
Temperature Min ( $T_{smin}$ )	150°C
Temperature Max ( $T_{smax}$ )	200°C
Time( $t_s$ )from ( $T_{smin}$ to $T_{smax}$ )	60---180 seconds.
Ramp---up rate ( $T_L$ to $T_p$ )	3°C/seconds max.
Liquidous temperature( $T_L$ )	217°C
Time( $t_L$ ) maintained above $T_L$	60---150 seconds
Peak package body temperature( $T_p$ )	260°C max
Time ( $t_p$ ) within 5°C of the specified classificaon temperature( $T_c$ ).	20---40 seconds max
Ramp---down rate ( $T_p$ to $T_L$ )	6°C/second max
Time 25°C to peak temperature	8 min max



## Pre---caution for use (注意事项)

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### **Caution**

1. Reflow soldering is recommended not to be done more than two times. In the case of more than 24 hours passed soldering after first, LEDs will be damaged.
2. Repairs should not be done after the LEDs have been soldered. When repair is unavoidable, suitable tools must be used.
3. Die slug is to be soldered.
4. When soldering, do not put stress on the LEDs during heating.
5. After soldering, do not warp the circuit board.

### **Notes on EMC Series soldering:**

1. Recommend to use reflow machine.
2. Recommend to use heating plate soldering.
3. Manual soldering is not recommended.

### **Notes on reflow process:**

1. To confirm whether the actual temperature curve in the reflow soldering conditions comply with recommended conditions. LEDs are guaranteed for one time reflow.
2. During reflow process do not apply force on LED active area.
3. After reflow process, PCB board should be cooled down before packing or storage.



## Pre---caution for use (注意事项)

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### 注意:

1. 回流焊建议不要超过两次.
2. LED 焊接后不建议重工。当重工不可避免时,必须使用合适的工具.
3. 不可虚焊.
4. 焊接加热过程中,请勿施加压力于 LED 表面 .
5. 焊接后,请勿弯曲电路板.

### 焊接注意事项:

1. 建议使用回流焊机器。
2. 建议使用加热板焊接。
3. 不建议手动焊接。

### 回流焊注意事项:

1. 确保实际温度曲线与回流焊接条件相符合。
2. 在回流过程中, 请勿施加压力于 LED 表面 。
3. 回流后,PCB 板在包装或存储前需冷却至常温。



Revision record 修订记录				
DOC.NO 文件编号	Version 版本	Page 页数	Content of change 变更内容	Date 日期
SZRSPSA-3C-048	A00	21	/	2019/10/21